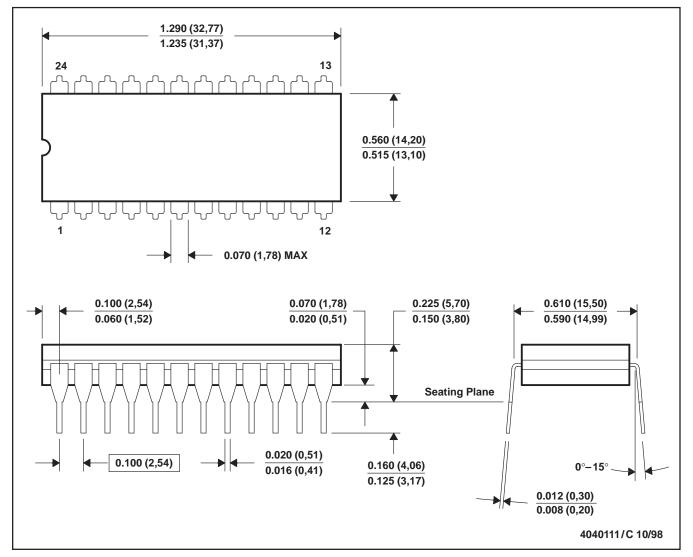
MECHANICAL DATA

MCER006A - JANUARY 1995 - REVISED JUNE 1999

JW (R-GDIP-T24)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD GDIP1-T24



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